COMBINED DECLARATION AND POWER OF ATTORNEY

As the below named inventor, I hereby declare that:

the specification of which

My residence, post office address and citizenship are as stated below next to my name and that I believe I am an original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

FLIP-CHIP PACKAGE AND FABRICATING PROCESS THEREOF

X							
_	was filed on as Application Seria	ıl No	and was amended on_		·		
app app fore	cification, including the I acknowledge the lication in accordance I hereby claim foreightication(s) for patent	e claims, as amende duty to disclose info with Title 37, Code on priority benefits un or inventor's certificatent or inventor's certificated:	and understand the content of by any amendment referred mation which is material to be federal Regulations, § 1 der Title 35, United States Cate listed below and have difficate having a filing date be	ed to above. the patent 56(a). Code, § 119 also identifi	ability of this of any foreign ed below any		
	Number	Country	Date Filed(yyyy/mm/dd)	Yes	No		
	92104000	Taiwan, R.O.C.	2003/2/26	×			
ŗ		e Patent and Tradem (Reg. No. 43,330	6) Charles Liu		39,081)		
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COMBINED DECLARATION AND POWER OF ATTORNEY CONTINUED

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patents issued thereon.

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